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shown). FIG. 1 shows a die up die or chip 10 positioned in the package with its contact points 13 and 14 arranged on the top surface. The direction that this top surface is facing defines the up direction. Notice that the leads 15 and 16 make connections to the chip on the upward facing surface of the chip 10. FIG. 2 shows a die down die or chip 20 with its contact points 22 and 23 on a surface that is facing in the down direction. Notice that the leads 24 and 25 make connections to the chip on the downward facing surface of the chip 20.

Note that if the die down chip (downward facing chip) 20 is flipped (so that its contact points 24 and 25 now face upward) and placed into the die up package of FIG. 1 that the contacts 24 and 25 would be reversed left to right. The result is a die down chip 20 cannot be flipped and directly mounted into a die up package. The present invention addresses this limitation.

REMARKS:

The above definitions provide a direction reference for understanding the application and the claims as amended.

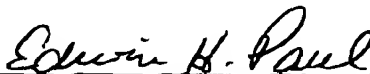
No new matter is added. Please refer to the first part of the Summary of the present invention. If there is still some misunderstanding, applicant's attorney, cited below, would appreciate a call from the Examiner.

None of the references cited or others are known provide this conversion of the orientation to allow a die-down chip to be mounted in a die-up package as the present invention so provides.

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All the claims distinguish the cited references and are now allowable. Please charge any additional fee occasioned by this paper to our Deposit Account No. 03-1237.

Respectfully submitted,



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